



Material Content Data Sheet



Sales Product Name		BFP 650F H6327		Issued		27. September 2017		
MA#		MA000895778						
Package		PG-TSFP-4-1		Weight*		1.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.04		376	
	noble metal	gold	7440-57-5	0.003	0.15		1457	
	inorganic material	silicon	7440-21-3	0.024	1.27	1.46	12701	14534
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		79	
	non noble metal	titanium	7440-32-6	0.001	0.04		394	
	non noble metal	chromium	7440-47-3	0.002	0.12		1183	
	non noble metal	copper	7440-50-8	0.734	39.25	39.42	392517	394173
wire	noble metal	gold	7440-57-5	0.007	0.38	0.38	3752	3752
encapsulation	organic material	carbon black	1333-86-4	0.010	0.51		5133	
	plastics	epoxy resin	-	0.206	11.03		110348	
	inorganic material	silicondioxide	60676-86-0	0.744	39.77	51.31	397765	513246
leadfinish	non noble metal	tin	7440-31-5	0.049	2.62	2.62	26166	26166
plating	noble metal	silver	7440-22-4	0.090	4.81	4.81	48129	48129
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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